PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4275177

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the CONVEYING PARTY DATA previously recorded on Reel 041238 Frame 0386. Assignor(s) hereby confirms the ASSIGNMENT.

CONVEYING PARTY DATA

Name	Execution Date
QINGQING LIANG	05/16/2011
HUICAI ZHONG	05/16/2011

RECEIVING PARTY DATA

Name:	INSTITUTE OF MICROELECTRONICS, CHINESE ACADEMY OF SCIENCES
Street Address:	NO. 3 BEITUCHENG WEST ROAD
Internal Address:	CHAOYANG DISTRICT
City:	BEIJING
State/Country:	CHINA
Postal Code:	100029

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13133061

CORRESPONDENCE DATA

Fax Number: (212)704-6288

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: IPservicesNYC@troutmansanders.com
Correspondent Name: TROUTMAN SANDERS LLP
Address Line 1: 875 THIRD AVENUE
Address Line 2: SUITE 1700
Address Line 4: NEW YORK, NEW YORK 10022

ATTORNEY DOCKET NUMBER:	239280.000032
NAME OF SUBMITTER:	RALUCA ONER
SIGNATURE:	/RALUCA ONER/
DATE SIGNED:	02/15/2017

Total Attachments: 4
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PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
LIANG QINGQING	05/16/2011
ZHONG HUICAI	05/16/2011

RECEIVING PARTY DATA

Name:	INSTITUTE OF MICROELECTRONICS, CHINESE ACADEMY OF SCIENCES
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13133061

CORRESPONDENCE DATA

Fax Number: (212)704-6288
Email: IPservicesNYC@troutmansanders.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name: TROUTMAN SANDERS LLP
Address Line 1: 875 THIRD AVENUE
Address Line 2: SUITE 1700
Address Line 4: NEW YORK, NEW YORK 10022

ATTORNEY DOCKET NUMBER:	239280.000032
NAME OF SUBMITTER:	RALUCA ONER
Signature:	/RALUCA ONER/
Date:	02/13/2017

Total Attachments: 2
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EPAS ID: PAT4271581
Receipt Date: 02/13/2017

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PATENT
REEL: 041721 FRAME: 0216

ASSIGNMENT

WHEREAS I, Liang, Qingqing, [hereinafter referred to Assignor], have made an invention entitled: **SEMICONDUCTOR DEVICE STRUCTURE AND METHOD FOR MANUFACTURING THE SAME** for which I am the listed inventor for the application for United States Letters Patent referred to below as the Formal Application:.

WHEREAS **INSTITUTE OF MICROELECTRONICS, CHINESE ACADEMY OF SCIENCES** whose mailing address is **No. 3 Beitucheng West Road, Chaoyang District, Beijing 100029, P. R. China** (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the above-identified Formal Application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I, as Assignor, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, MY entire right, title, and interest in and to this invention, the above-identified patent application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patents which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I HEREBY covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment;

AND, I HEREBY further covenant and agree that I will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to ME respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may by necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuing, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent prosecution for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns;

AND, I HEREBY further covenant and agree that I will assign, and hereby do assign, to Assignee, its lawful successors and assigns, MY entire right, title, and interest in and to any and all patent applications, both United States and foreign, and all Letters Patent that may be granted thereon, that claim priority to this invention or to the above-identified provisional or non-provisional applications in any manner, such applications specifically including, but not limited to, divisionals, continuations, continuations-in-part, and all other provisional and non-provisional applications.

Assignor: Liang, Qingqing

Address of Assignor:
No. 3 Beitucheng West Road, Chaoyang District
Beijing 100029, P. R. China

Assignor's Signature

Date: 05/16/2011

ASSIGNMENT

WHEREAS I, Zhong, Huicai, [hereinafter referred to Assignor], have made an invention entitled: **SEMICONDUCTOR DEVICE STRUCTURE AND METHOD FOR MANUFACTURING THE SAME** for which I am the listed inventor for the application for United States Letters Patent referred to below as the Formal Application:.

WHEREAS **INSTITUTE OF MICROELECTRONICS, CHINESE ACADEMY OF SCIENCES** whose mailing address is **No. 3 Beitucheng West Road, Chaoyang District, Beijing 100029, P. R. China** (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the above-identified Formal Application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I, as Assignor, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, MY entire right, title, and interest in and to this invention, the above-identified patent application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patents which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I HEREBY covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment;

AND, I HEREBY further covenant and agree that I will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to ME respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may by necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuing, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent prosecution for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns;

AND, I HEREBY further covenant and agree that I will assign, and hereby do assign, to Assignee, its lawful successors and assigns, MY entire right, title, and interest in and to any and all patent applications, both United States and foreign, and all Letters Patent that may be granted thereon, that claim priority to this invention or to the above-identified provisional or non-provisional applications in any manner, such applications specifically including, but not limited to, divisionals, continuations, continuations-in-part, and all other provisional and non-provisional applications.

Assignor: Zhong, Huicai

Address of Assignor:
No. 3 Beitucheng West Road, Chaoyang District
Beijing 100029, P. R. China

Assignor's Signature

Date: 5/16/2011